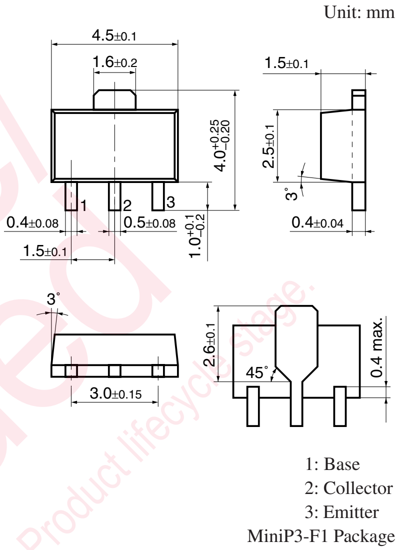
UNR7231 (UN7231)

Silicon NPN epitaxial planar type



For low-frequency amplification

■ Features

- High forward current transfer ratio h_{FE}
- Costs can be reduced through downsizing of the equipment and reduction of the number of parts.

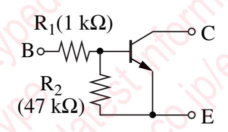
■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	20	V
Collector-emitter voltage (Base open)	V_{CEO}	20	V
Collector current	I_C	0.7	A
Peak collector current	I_{CP}	1.5	A
Total power dissipation *	P_T	1.0	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

Note) *: Printed circuit board: Copper foil area of 1 cm^2 or more, and the board thickness of 1.7 mm for the collector portion

Marking Symbol: IC

Internal Connection



■ Electrical Characteristics $T_a = 25°C \pm 3°C$

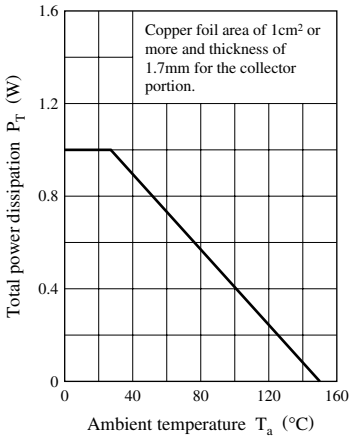
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 10\ \mu A$, $I_E = 0$	20			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 1$ mA, $I_B = 0$	20			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 15$ V, $I_E = 0$			1	µA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 15$ V, $I_B = 0$			10	µA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 14$ V, $I_C = 0$			0.5	mA
Forward current transfer ratio *	h_{FE}	$V_{CE} = 10$ V, $I_C = 150$ mA	800		2 100	—
Collector-emitter saturation voltage *	$V_{CE(sat)}$	$I_C = 500$ mA, $I_B = 5$ mA			0.4	V
Input resistance	R_1		0.7	1.0	1.3	kΩ
Resistance ratio	R_1/R_2		0.016	0.021	0.025	—
Transition frequency	f_T	$V_{CB} = 20$ V, $I_E = -20$ mA, f = 200 MHz		55		MHz

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

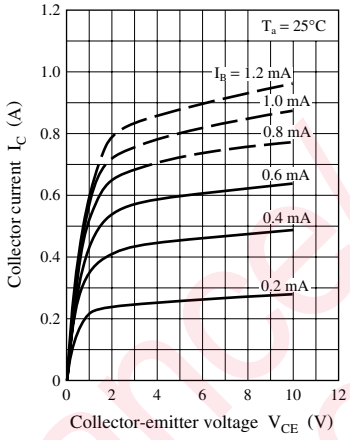
2. *: Pulse measurement

Note) The part number in the parenthesis shows conventional part number.

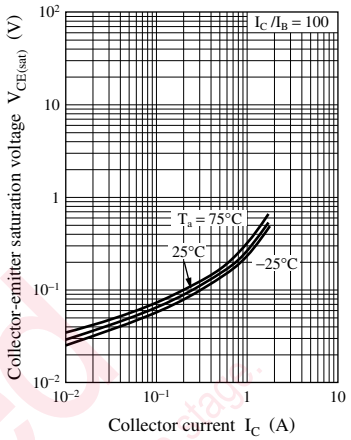
P_T — T_a



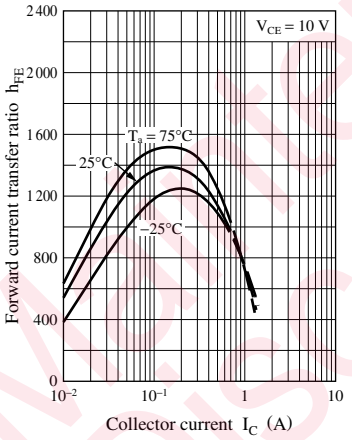
I_C — V_{CE}



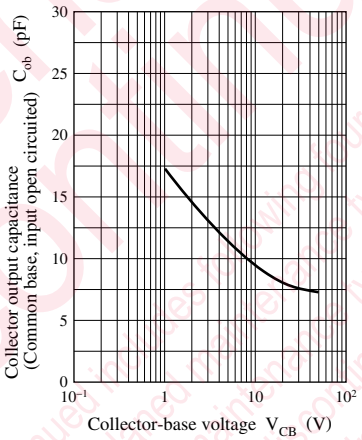
$V_{CE(sat)}$ — I_C



h_{FE} — I_C



C_{ob} — V_{CB}



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